

IN THE CLAIMS:

All pending claims are set forth below. Cancelled and withdrawn claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~strikethrough~~. The status of each claim is indicated with one of (original), (currently amended), (previously amended), (cancelled), (withdrawn), (new), (previously added), (reinstated - formerly claim #), (previously reinstated), (re-presented - formerly dependent claim #), or (previously re-presented). Please AMEND claims and ADD new claims, in accordance with the following:

1. (CANCELED)
2. (CANCELED)
3. (CANCELED)
4. (CANCELED)
5. (CANCELED)

6. (CURRENTLY AMENDED) A process of producing a semiconductor package comprising ~~the steps of:~~

forming a plurality of pad segments forming each ~~pad~~ of plural pads to which each external connection terminal is bonded while opening up spaces between the pad segments sufficient for passing interconnections ~~therebetween~~ therethrough when forming an interconnection layer including interconnection patterns and the pads on an insulating substrate or insulating layer; _i

forming a protective layer covering said interconnection layer other than at portions of pads formed by said plurality of pad segments and said insulating substrate or insulating layer; _i and

bonding one external connection terminal to each pad formed by said plurality of pad segments exposed from said protective layer.

7. (CURRENTLY AMENDED) A process of producing a semiconductor module as set forth in claim 6, further comprising ~~the steps of:~~

forming a protective film; _i and

forming a plating film for improving adhesion when bonding the external connection terminals to the pad segments exposed from said protective film.

8. (NEW) A process of producing a semiconductor package comprising:
forming a plurality of pads on an insulating substrate, each of the plurality of pads having plural pad segments separated by spaces therebetween; and
forming interconnection layers on the insulating substrate, each interconnection layer connecting with at least one pad segment of each of the plurality of pads to connect the at least one pad segment of each pad with other interconnection layers within the semiconductor package while the pad segments not connected with the interconnection layers to be connected externally of the semiconductor package.